

Title (en)
WAFER MARKING

Title (de)
WAFERMARKIERUNG

Title (fr)
MARQUAGE DE GALETTES

Publication
EP 1002338 A1 20000524 (DE)

Application
EP 98948693 A 19980730

Priority
• DE 9802187 W 19980730
• DE 19733410 A 19970801

Abstract (en)
[origin: DE19733410A1] A wafer marking is constituted by a plurality of soft marks produced in the surface of a wafer. These soft marks are at least 4 μm deep, have an inner diameter of at least 50 μm and in a particularly advantageous manner have a minimum rise at their surface of 0.2. These recesses (12) can be produced by means of a corresponding technology with depths of up to 6 μm .

IPC 1-7
H01L 23/544

IPC 8 full level
H01L 21/02 (2006.01); **H01L 23/544** (2006.01); **H01L 29/30** (2006.01)

CPC (source: EP KR US)
H01L 23/544 (2013.01 - EP KR US); **H01L 2223/54433** (2013.01 - EP US); **H01L 2223/54473** (2013.01 - EP US);
H01L 2924/0002 (2013.01 - EP US)

Citation (search report)
See references of WO 9907016A1

Designated contracting state (EPC)
DE FR GB IE IT

DOCDB simple family (publication)
DE 19733410 A1 19990218; EP 1002338 A1 20000524; JP 2001512293 A 20010821; KR 20010022516 A 20010315; US 6261382 B1 20010717;
WO 9907016 A1 19990211

DOCDB simple family (application)
DE 19733410 A 19970801; DE 9802187 W 19980730; EP 98948693 A 19980730; JP 2000505651 A 19980730; KR 20007001104 A 20000201;
US 49579500 A 20000201